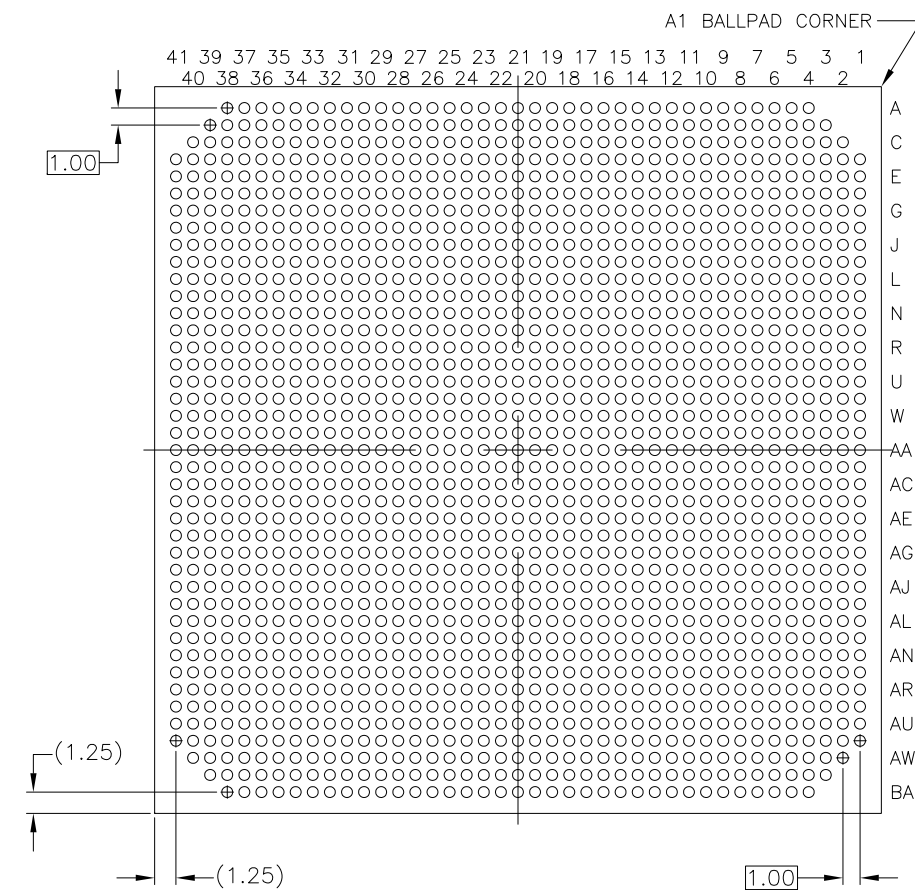
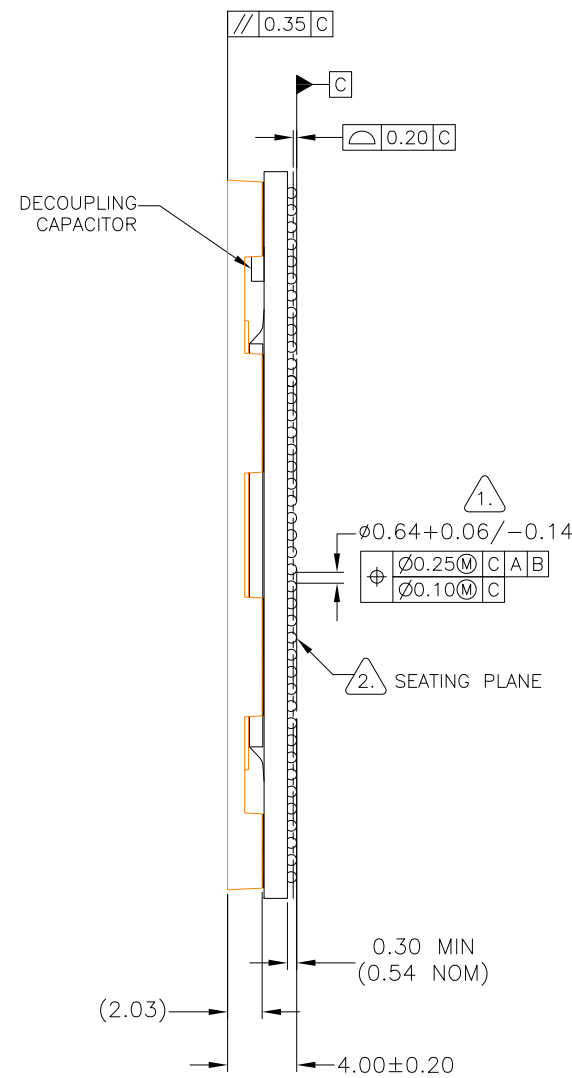
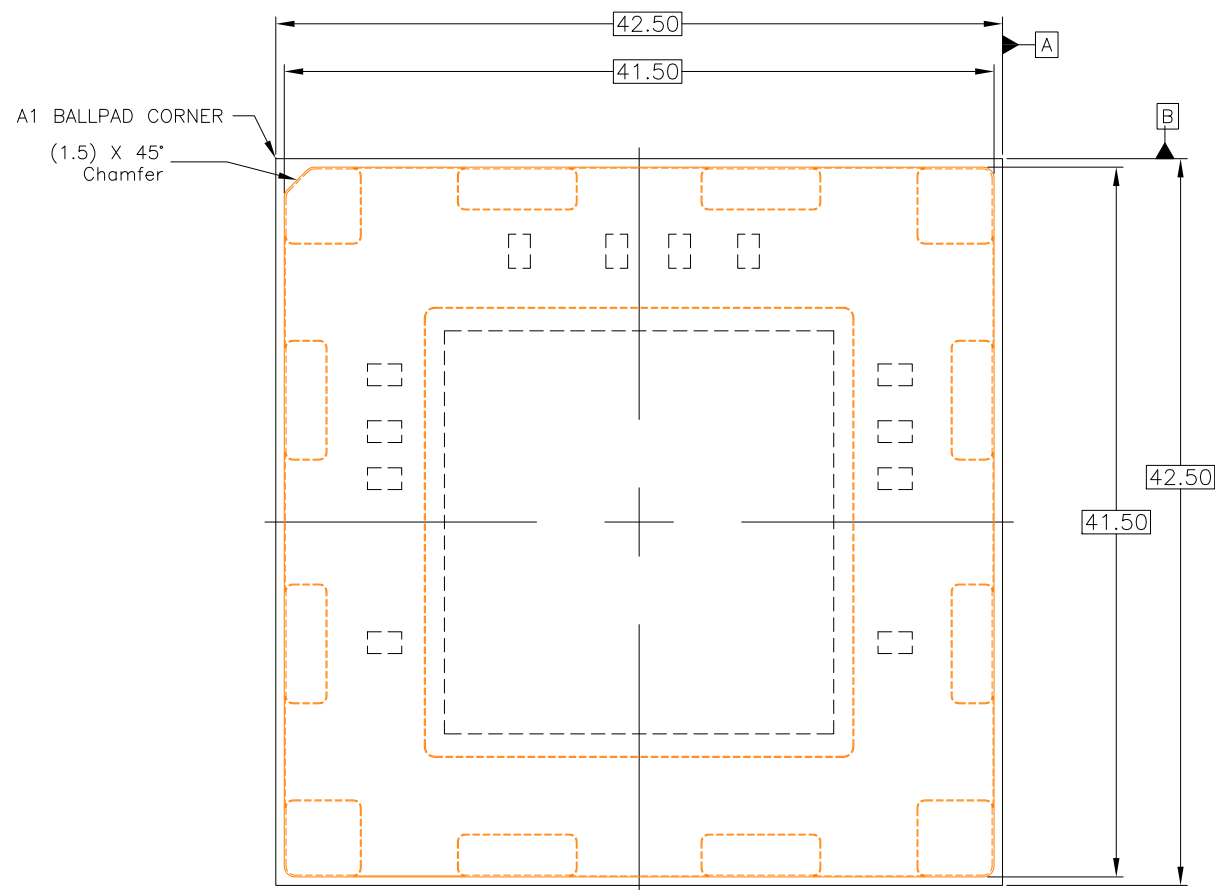


ECN NO.	REV.	DESCRIPTION OF CHANGE	ECN DATE	ORIGINATOR
20190108	0	Preliminary Drawing	12/14/18	Erwin Q.
20200074	1	Revise title from RT4G150M-FCG1657 to RT4G150-FCG1657M, add vendor dwg #.	02/24/20	Erwin Q.



NOTES:

- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

GENERAL TOLERANCE		PROJECTION:		MICROSEMI CORPORATION, SOC GROUP		
UNLESS OTHERWISE SPECIFIED				3850 N 1st St San Jose, CA 95134		
DECIMAL X.X ±0.1 X.XX ±0.05 X.XXX ±0.030	ANGULAR ±1°	APPROVALS	DATE	TITLE: RT4G150-FCG1657M, 42.5 MM X 42.5 MM, 1.0 MM PITCH, 1657 SOLDER BALLS, FLIP CHIP, PACKAGE OUTLINE DRAWING		
INTERPRET DIM AND TOL PER ASME Y14.5M - 2009		DRAWN: Erwin Q.	02/24/20	VENDOR NAME: Amkor Technology	DWG. NUMBER: 1-14-12021	REV: 1
DIMENSIONS: Millimeters (mm)	ENG'R:	CHECKED: Raymond K.	02/24/20	PART NUMBER: --	VENDOR DWG. NUMBER: 0851877PO	REV: D
	RELEASED:				SCALE: NONE	SHEET 1 OF 1